November 13th, 2026

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Q&A Regarding Financial Results Briefing for the 3rd Quarter of FY2026

We hereby disclose the following anticipated questions and our responses regarding the financial results for the 3rd Quarter of the fiscal year ending December 31, 2026, announced today

(RST Group (partial list))

SEGMENT	Company Name (short name)	Production Site	Business
Wafer Reclaim Business	RS Technologies	Sanbongi (Japan)	Reclaimed Wafer/Sales Wafer
	RS Taiwan	Tainan	
Pirme Wafer Business	GRITEK/Shandong GRITEK	Beijing/ Dezhou (China)	Silicon、FZ Ingot 5, 6, 8 inch Prime Wafer
	SGRS(equity method affiliate)	Dezhou (China)	12inch Prime Wafer
Semiconductor-related Equipment and Materials Business	RS Technologies	—	Semiconductor manufacturing and inspection equipment, electronic components
	Union Electronics Solutions	—	Semiconductor manufacturing and inspection equipment, electronic components
	DG Technologies	Kamisu, Kurihara (Japan)	Consumable parts for semiconductor equipment
	LE System	Namie(Japan)	VRFB Electrolyte/Energy related business
	RS Energy / RS Energy (Panzhihua)	Panzhihua (China)	VRFB Electrolyte
	RSPDH	Huizhou (China)	Optical Pickup/Automotive Camera Module

<Reclaimed Wafer Business>

Q1: Trends in reclaimed wafer ASPs in Q3 and the outlook for future price revisions

A1: Reclaimed wafer ASPs increased by several percent quarter on quarter in Q3.
We refrain from commenting on specific price revisions due to confidentiality with customers. However, in light of recent supply-demand conditions and rising costs, we regard efforts to achieve appropriate pricing as one of our key initiatives. As reclaimed wafer sales are primarily based on short-term contracts, we intend to improve ASPs gradually.
In addition, we will continue to expand orders for advanced applications, which command higher prices. At the same time, conventional high-volume applications remain important for efficient factory operations, profitability, and maintaining our customer base. We will therefore optimize our product mix while considering market conditions and customers' capital expenditure trends.

Q2: Reasons for the 1.3 percentage-point year-on-year decline in the operating margin of the reclaimed wafer business (Financial Result Page 5)

A2: The main factor was an increase in depreciation associated with capacity expansion. Personnel and infrastructure costs also rose, but the impact has been partially absorbed by higher sales volume and continued high utilization.
* Depreciation by segment is disclosed annually and is available in the segment information in the full-year financial results.

Q3: Reasons for the slowdown in year-on-year revenue growth in the reclaimed wafer business (Financial Result Page 5)

A3: Revenue increased 7.1% year on year in the current period, compared with an 18.0% increase in the same period of the previous year.
In addition to the timing of capacity ramp-ups, the product mix between reclaimed wafers and wafers for resale affected growth. In the same period of the previous year, there was a temporary increase in demand for wafers for resale ahead of the start-up of a customer's new plant. In the current period, amid tight global wafer supply-demand conditions, both the revenue contribution and shipment volume of wafers for resale declined year on year.
We recognize that this situation may continue for some time. Meanwhile, demand for reclaimed wafers is increasing under these conditions, and we will steadily proceed with our capital expenditure plan to meet future market demand.
* Please refer to page 29 of the financial results presentation for wafers for resale and to the segment information in the quarterly financial results for the quarterly revenue mix.

Q4: Progress on capital expenditure in the reclaimed wafer business and the full-year outlook (Financial Results Page 13)

A4: As of the end of Q3, the planned capacity expansion at the Tainan Plant for the current fiscal year, an additional 30,000 wafers per month, had been completed.
Sanbongi Plant No. 7 began phased operations in November and is expected to reach monthly production capacity of 40,000 wafers by year-end. Capacity will be increased gradually, with the contribution to earnings expected to materialize progressively.
Current demand remains strong, and we expect full-year revenue and profit to increase year on year.

<Prime Wafer Business>

Q5: Q3 performance and outlook for silicon parts

A5: Silicon parts sales volume increased by more than 100% year on year and by more than 20% quarter on quarter, driven mainly by growth in sales to South Korea.
Selling prices remained stable.
Although quarterly fluctuations are expected because sales are primarily based on short-term contracts, we believe demand is on an upward trend and will make planned capital investments to meet this demand.

Q6: Pricing Trends for 8inch Prime Wafer (Financial Results Page 34)

A6: ASPs have improved slightly from last year's sharp decline, but our pricing does not fully track global wafer makers. Our 8-inch wafer business is mainly focused on China and power devices, particularly heavily doped wafers for high-voltage applications. As demand is largely driven by this niche Chinese market, the impact of global wafer pricing is limited.
Going forward, we aim to improve ASPs by increasing high-value-added products such as Epi, FZ, and MCZ wafers. At the same time, volume products remain important for efficient factory operations. We will continue to optimize our product mix based on market conditions.

Q7: Risk that demand for silicon wafers for power devices in China will shift to SiC or GaN (Financial Results Page 36)

A7: Given the active research, development, and technological innovation involving new materials, we recognize that such a shift may occur over the long term. From the current to medium-term perspective, however, we expect demand for silicon to continue growing steadily due to its cost advantages and the widespread adoption of related equipment by device manufacturers.
Among silicon wafers, high-value-added products for power devices, including Epi, FZ, and MCZ wafers, can meet the requirements of high-performance power devices, including high-voltage applications that are difficult to address with conventional CZ wafers. By leveraging our accumulated technologies and further strengthening our initiatives in high-value-added products, we aim to maintain our medium- to long-term competitive advantage in the power device field.

Q8: Reasons for the decision to reorganize GRITEK (Financial Results Page37&38)

A8: We view the continued expansion of China's semiconductor market as a significant growth opportunity. Against this backdrop, we have decided to restructure GRITEK to establish an integrated operational framework covering silicon wafers ranging from 5, 6, and 8 inches to 12 inches. In the Chinese market, cost competitiveness and rapid decision-making, in addition to technological capabilities, are essential to improving competitiveness. Through this reorganization, we will integrate the use of management resources, including facilities, capital, personnel, technology, and customer relationships, to improve management efficiency.
The reorganization will also enable the Group to make effective use of single-crystal ingot production at the Inner Mongolia plant established this fiscal year and the technology of the Anhui Epi house acquired through M&A.
With both the external and internal conditions now in place, we determined that this is the optimal time to implement the reorganization.

Q9: Reasons for maintaining GRITEK as a consolidated subsidiary after the reorganization (Financial Results Page37&38)

A9: At present, we believe there are benefits to maintaining GRITEK as a consolidated subsidiary. GRITEK is currently working to stabilize the production and quality of 12-inch wafers in addition to 8-inch wafers, while building a sales track record in the Chinese market.
Beyond this, we are also considering expansion into global markets. Becoming a global integrated wafer manufacturer has been a major vision since our founding. To realize this vision, we believe it is important for RS Technologies, which has built relationships with semiconductor manufacturers worldwide through its reclaimed wafer business, and GRITEK to operate as one Group. Having listed companies in both Japan and China also provides numerous strategic benefits, including the creation of new business opportunities and partnerships.
GRITEK's value cannot be measured solely by the value of its shares and assets. After considering Group synergies and future growth opportunities comprehensively, we have decided to maintain consolidation at this time.

Q10: Acquisition prices for Shandong GRITEK and SGRS, and the impact on the medium-term management plan (Financial Results Page37)

A10: The enterprise values of both companies are currently under review. The reorganization is expected to be completed in 2027. We will promptly disclose further details, including the impact from FY2027 onward, once finalized.

Q11: Timing of SGRS's contribution to earnings

A11: As stated in the September 11, 2026 announcement, "Reorganization of Consolidated Subsidiaries (Prime Wafer Business)," SGRS recorded an operating loss of approximately ¥4.7 billion* and a net loss of approximately ¥4.0 billion* in FY2025. (*Converted at ¥23.5 per RMB)
At present, we believe the conditions for reaching the break-even point are monthly production capacity of approximately 300,000 wafers and stable shipments of prime wafers at a high utilization rate. Monthly production capacity of 300,000 wafers is expected to be established around 2029, although the timing may change depending on the progress of capital expenditure and market conditions.

Q12: Production and shipment volumes and pricing trends for SGRS's 12-inch wafers

A12: We refrain from providing specific comments on SGRS at this time because such information could affect GRITEK's share price.

<Semiconductor-related Equipment and Material Business>

Q13: Impact on the medium-term management plan of the October 9 announcement, "Dissolution of RS Precision Devices (Huizhou) Co., Ltd. (RSPDH) and the Discontinuation of Entry into the Automotive Camera Module Business"

A13: There is no impact on the current fiscal year's results, and our outlook for annual revenue of more than ¥10.0 billion remains unchanged. From the next fiscal year onward, there may be some impact because the planned entry into the automotive camera module business had been partially incorporated into our plan. We will provide an updated explanation of our plans for 2027 onward in February 2027, taking this matter into account.
This decision was made to concentrate management resources on our core businesses and strategic growth areas and to enhance corporate value over the medium to long term.